



**ES2A
THRU
ES2J**

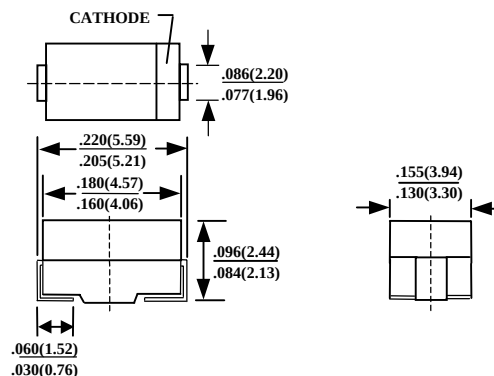
2A FAST EFFICIENT SURFACE MOUNT RECTIFIER

FEATURES

- LOW PROFILE PACKAGE
- PLASTIC PACKAGE HAS UNDERWRITERS LABORATORY 94V-0
- IDEAL FOR SURFACE MOUNTED APPLICATION
- GLASS PASSIVATED CHIP JUNCTI
- BULIT-IN STRAIN RELIEF DESIGN
- FAST EFFICIENT RECOVERY TIME FOR HIGH EFFICIENT
- HIGH TEMPERATURE SOLDERING : 250°C/10 SECONDS AT TERMINAL

MECHANICAL DATA

- CASE : JEDEC DO-214AA MOLDED PLAS BODY
- TERMINAL : SOLDER PLATED, SOLDERABLE PER MIL-STD-750 METHOD 2026
- POLARITY : COLOR BAND DENOTES CATHODE
- WEIGHT : 0.093 GRAMS



CASE:DO-214AA (SMB)
DIMENSIONS IN INCHES AND (MILLIMETERS)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

RATINGS AT 25°C AMBIENT TEMPERATURE UNLESS OTHERWISE SPECIFIED

SINGLE PHASE, HALF WAVE, 60 HZ, RESISTIVE OR INDUCTIVE LOAD.

FOR CAPACITIVE LOAD, DERATE CURRENT BY 20%

RATINGS	SYMBOL	ES2A	ES2B	ES2C	ES2D	ES2E	ES2G	ES2J	UNITS
MAXIMUM RECURRENT PEAK REVERSE VOLTAGE	V_{RRM}	50	100	150	200	300	400	600	V
MAXIMUM RMS VOLTAGE	V_{RMS}	35	70	105	140	210	280	420	V
MAXIMUM DC BLOCKING VOLTAGE	V_{DC}	50	100	150	200	300	400	600	V
MAXIMUM AVERAGE FORWARD RECTIFIED CURRENT AT $T_L=90^\circ\text{C}$	I_O	2.0							A
PEAK FORWARD SURGE CURRENT, 8.3ms SINGLE HALF SINE-WAVE SUPERIMPOSED ON RATED LOAD	I_{FSM}	50							A
TYPICAL JUNCTION CAPACITANCE (NOTE 1)	C_J	25							PF
TYPICAL THERMAL RESISTANCE (NOTE 2)	$R_{\theta JL}$	20							°C/W
STORAGE TEMPERATURE RANGE	T_{STG}	- 55 TO + 150							°C
OPERATING TEMPERATURE RANGE	T_{OP}	- 55 TO + 150							°C

ELECTRICAL CHARACTERISTICS ($A_T T_A=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

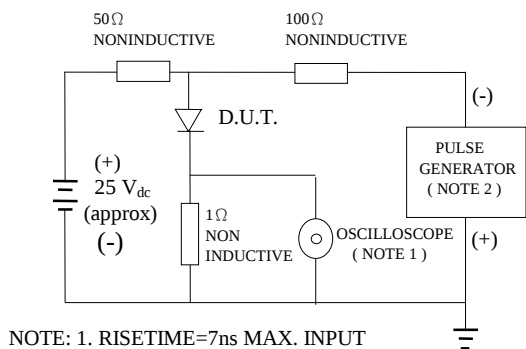
CHARACTERISTICS	SYMBOL	ES2A	ES2B	ES2C	ES2D	ES2E	ES2G	ES2J	UNITS
MAXIMUM FORWARD VOLTAGE AT $I_O=2.0A$	V_F	0.90				1.25		1.85	V
MAXIMUM REVERSE CURRENT AT 25°C	I_R	5							μA
MAXIMUM REVERSE CURRENT AT 100°C	I_R	150							μA
MAXIMUM REVERSE RECOVERY TIME (NOTE 3)	T_{RR}	25							nS
MARKING		ES2A	ES2B	ES2C	ES2D	ES2E	ES2G	ES2J	

NOTE :

1. MEASURED AT 1 MHZ AND APPLIED REVERSE VOLTAGE OF 4.0 VOLTS
2. THERMAL RESISTANCE FROM JUNCTION TO AMBIENT AND JUNCTION TO LEAD P.C.B. MOUNTED ON 0.3×0.3"(8.0×8.0mm) COPPER PAD AREAS
3. REVERSE RECOVERY TEST CONDITIONS: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

RATINGS AND CHARACTERISTIC CURVE ES2A THRU ES2J

FIG. 1-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTE: 1. RISE TIME = 7ns MAX. INPUT IMPEDANCE = 1 MEGOHM 22PF
2. RISE TIME = 10ns MAX. SOURCE IMPEDANCE = 50 OHMS

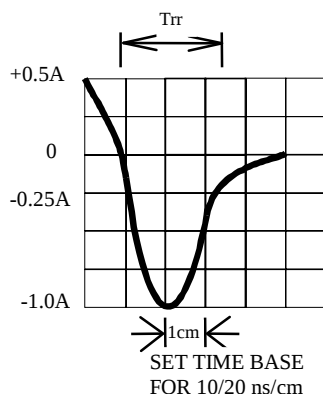


FIG. 2-TYPICAL FORWARD CURRENT DERATING CURVE

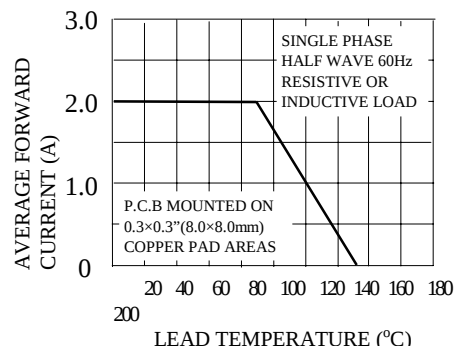


FIG. 3-TYPICAL REVERSE CHARACTERISTICS

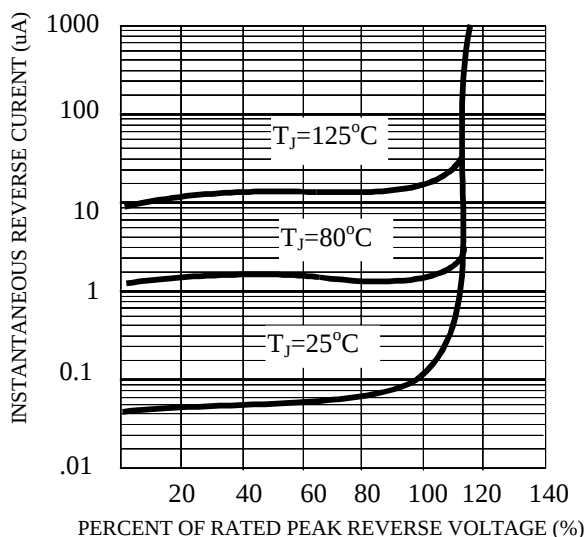


FIG. 4-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

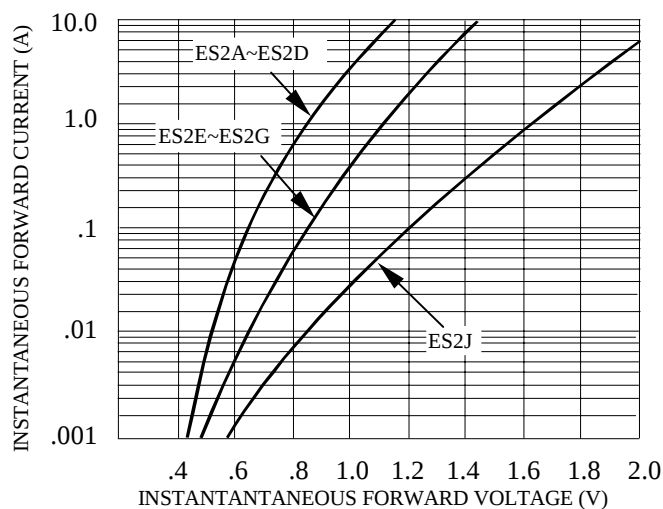


FIG. 5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

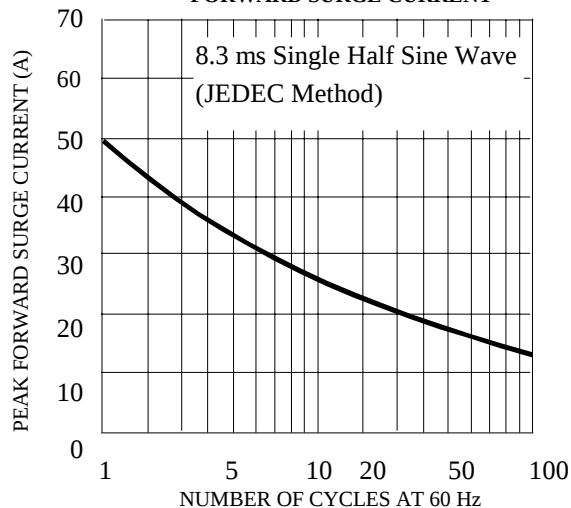


FIG. 6-TYPICAL JUNCTION CAPACITANCE

